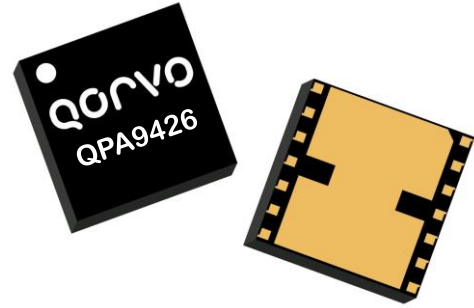


General Description

The QPA9426 is a high-linearity two-stage power amplifier in a low-cost surface-mount package with on-chip bias control and temperature compensation circuits, suitable for small cell base station applications.

QPA9426 provides 34 dB gain and +27 dBm linear power over the 2.5 – 2.7 GHz frequency range which includes 3GPP bands 7, 38 & 41. The amplifier is able to achieve -47 dBc ACLR at +27 dBm output power using 20 MHz LTE signal.

The QPA9426 integrates two high performance amplifier stages onto a module to allow for a compact system design and requires very few external components for operation. The amplifier is bias adjustable allowing the amplifier's power consumption to be optimized. The QPA9426 is available in a lead-free/RoHS-compliant 7 x 7 mm surface mount package.

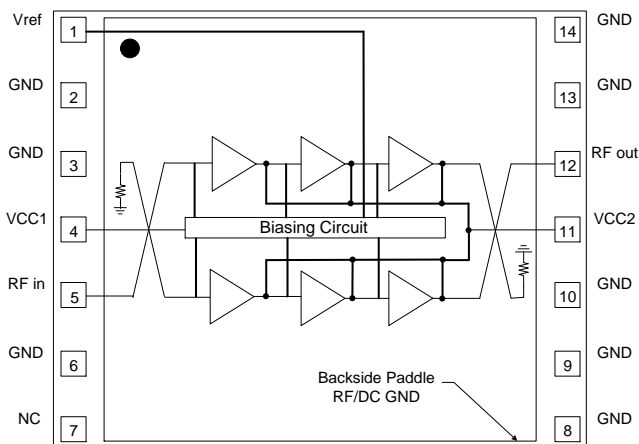


7 x 7 mm Leadless SMT Package

Product Features

- 2.5 – 2.7 GHz Frequency Range
- Fully Integrated, 2 Stage Power Amplifier
- Internally Matched 50 Ω Input/Output
- -47 dBc ACLR at Pavg = +27 dBm
- 34 dB Gain
- 14% PAE at +27 dBm
- 420 mA Quiescent Current
- On-chip Bias Control and Temp. Comp. Circuit

Functional Block Diagram



Top View

Applications

- Small Cell / Picocell
- Bands 7, 38, 41
- Enterprise Femtocell
- Customer Premises Equipment (CPE)
- Data Cards and Terminals
- Distributed Antenna Systems (DAS)
- Booster Amps, Repeaters

Ordering Information

| Part No. | Description |
|---------------|-----------------------------------|
| QPA9426SR | 100pcs on 7" reel |
| QPA9426TR13 | 2,500pcs on a 13" reel (standard) |
| QPA9426PCB401 | 2.5 – 2.7 GHz Evaluation Board |

Absolute Maximum Ratings

| Parameter | Rating |
|-----------------------------------|----------------|
| Storage Temperature | -55 to +150 °C |
| Supply Voltage (V _{CC}) | +6 V |
| V _{ref} | +3.5 V |
| RF Input Power, CW, 50Ω, T=25°C | +10 dBm |

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

Recommended Operating Conditions

| Parameter | Min | Typ | Max | Units |
|---|-------|-------|-------|-------|
| V _{CC1} , V _{CC2} | +3.6 | +4.5 | +5.25 | V |
| V _{ref} | +2.75 | +2.85 | +2.95 | V |
| T _{CASE} | -40 | | +85 | °C |
| T _j at T _{CASE} max | | | +156 | °C |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

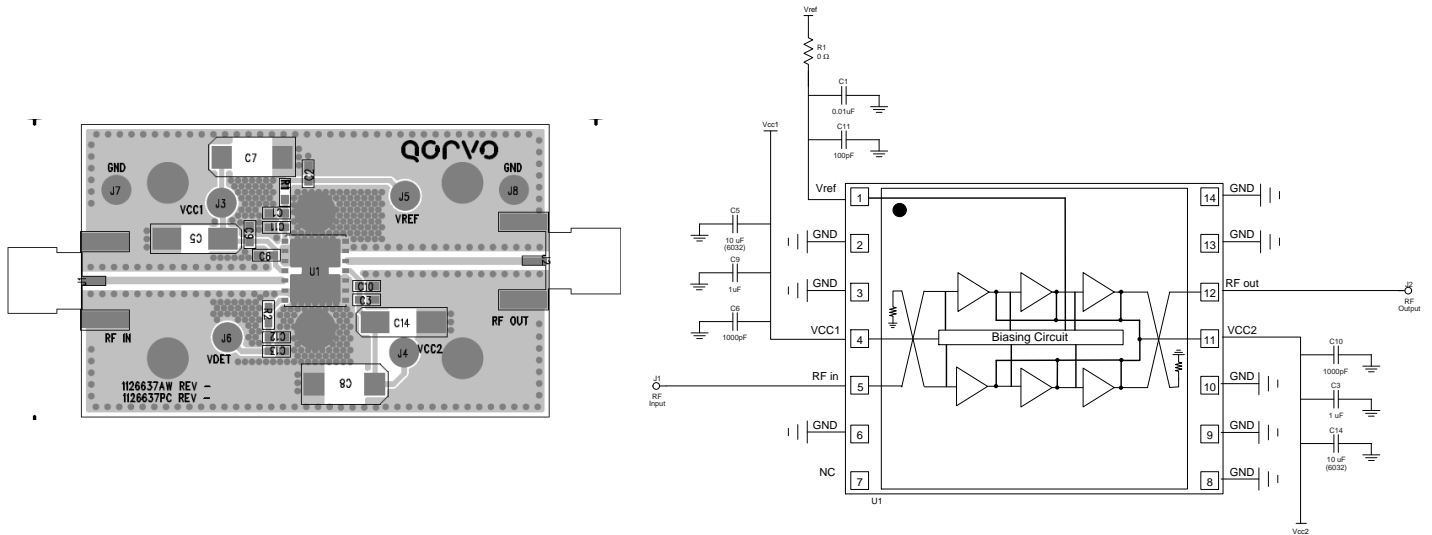
Electrical Specifications

| Parameter | Conditions ⁽¹⁾ | Min | Typ | Max | Units |
|--|--|------|------|------|-------|
| Operational Frequency Range | | 2.5 | | 2.7 | GHz |
| Test Frequency | | | 2.6 | | GHz |
| Gain | | 30.5 | 33 | 35 | dB |
| Input Return Loss | | | 20 | | dB |
| Output Return Loss | | | 20 | | dB |
| P1dB | | | 35.5 | | dBm |
| ACLR | P _{OUT} = +27dBm, 20 MHz LTE E-TM1.1, 9.5dB PAR | -45 | -47 | | dBc |
| Power Added Efficiency | P _{OUT} = +27dBm, 20 MHz LTE E-TM1.1, 9.5dB PAR | 12 | 14 | | % |
| Quiescent Current, I _{CCQ} ² | V _{CC1} + V _{CC2} | 330 | 420 | 500 | mA |
| Leakage Current | V _{CC} = +4.5 V, V _{ref} = 0 V | | 3 | 10 | μA |
| Reference Current, I _{ref} | V _{ref} = +2.85V | | 15 | 19 | mA |
| Operational Current, I _{CC} | P _{out} = +27 dBm | | 805 | 900 | mA |
| Switching Speed | Rise time (10%-90%) | | 650 | | ns |
| | Fall time (90%-10%) | | 500 | | ns |
| Spurious Output Level | P _{out} ≤ +27dBm, In & Out of band load VSWR ≤ 10:1 | | -60 | | dBc |
| VSWR survivability | No permanent degradation or failure | 10:1 | | | - |
| Harmonics | 2F ₀ (P _{out} = 27 dBm) | | -32 | -28 | dBc |
| | 3F ₀ (P _{out} = 27 dBm) | | -34 | -30 | dBc |
| | 4F ₀ (P _{out} = 27 dBm) | | -64 | -60 | dBc |
| Thermal Resistance, θ _{jc} | Module (junction to case) | | | 17.4 | °C/W |

Notes:

1. Test conditions unless otherwise noted: V_{CC1} = V_{CC2} = +4.5 V, V_{ref} = +2.85V, Temp = +25 °C, 50 Ω system.
2. Current through V_{CC1} does not vary with power. V_{CC1} provides the bias voltage to the current mirror circuit along with V_{ref} to set the bias point for the whole amplifier.

Evaluation Board Layout and Schematic

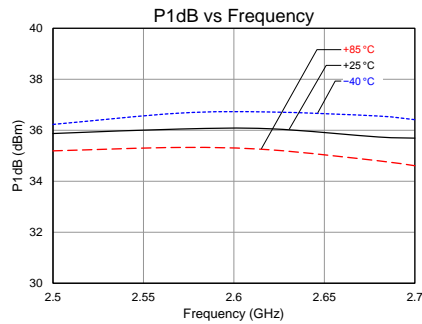
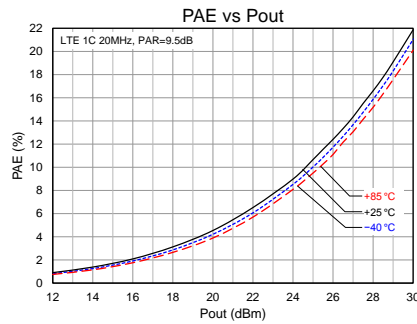
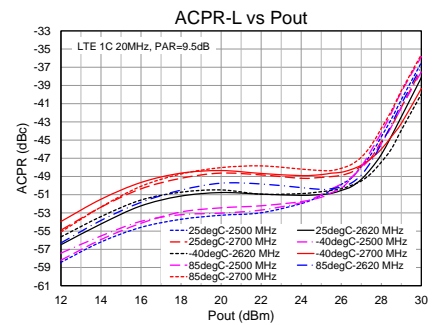
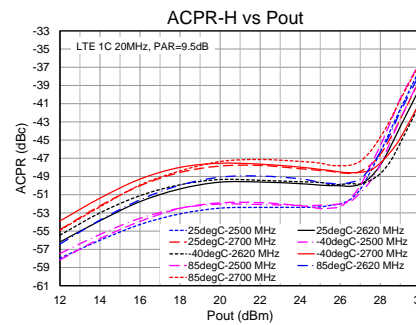
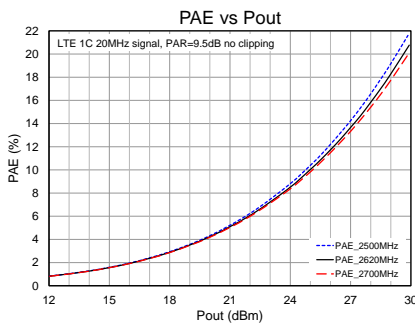
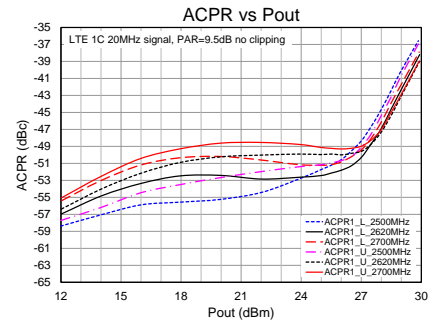
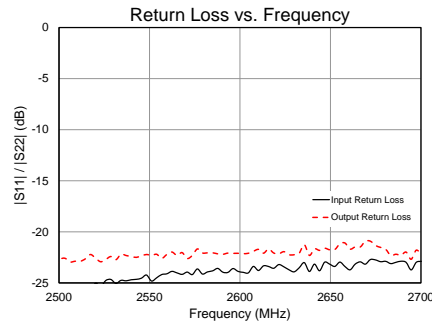
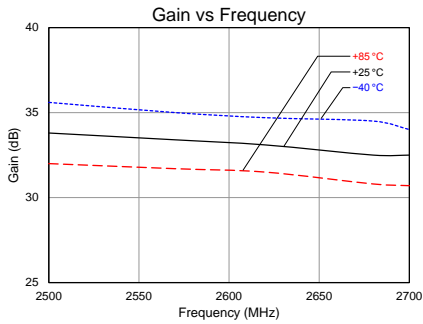


Bill of Material – Evaluation Board

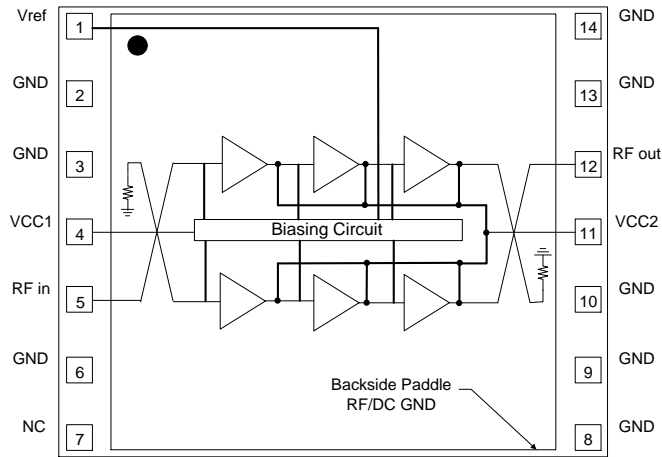
| Reference Des. | Value | Description | Manuf. | Part Number |
|----------------|---------|--------------------------------------|---------|-------------|
| n/a | n/a | Printed Circuit Board | | |
| U1 | n/a | High Linearity 0.5 W Power Amplifier | Qorvo | QPA9426 |
| R1 | 0 Ω | Resistor, Chip, 0603, 5% | various | |
| C1 | 0.01 uF | Capacitor, Chip, 0603, 5% | various | |
| C11 | 100 pF | Capacitor, Chip, 0603, 5% | various | |
| C3, C9 | 0.1 uF | Capacitor, Chip, 0603, 5% | various | |
| C5, C14 | 10 uF | Capacitor, Chip, 6032, 10%, Tantalum | various | |
| C6, C10 | 1000 pF | Capacitor, Chip, 0603, NPO/COG, 5% | various | |

Performance Plots

Test conditions unless otherwise noted: $V_{CC1} = V_{CC2} = +4.5V$, $V_{ref} = +2.85V$, $Temp. = +25^\circ C$



Pin Configuration and Description

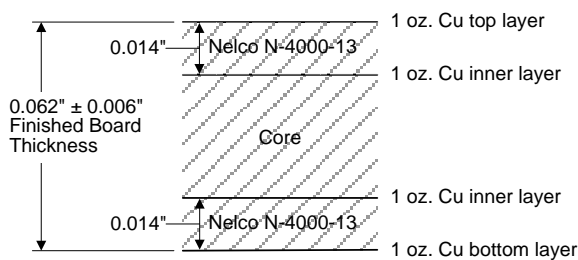


Top View

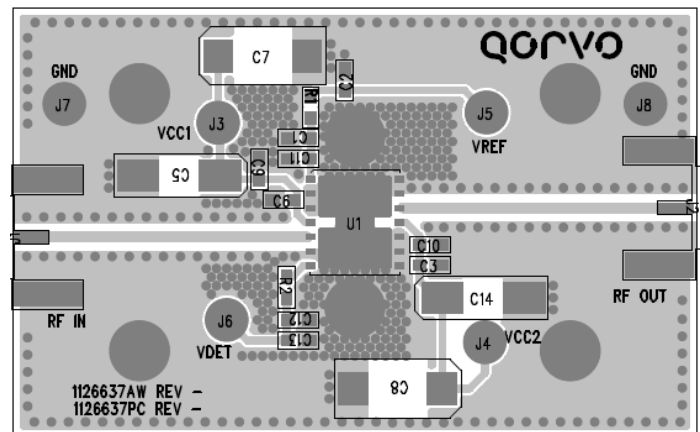
| Pad No. | Label | Description |
|---------------------------|-----------|---|
| 1 | Vref | Provides reference voltage for internal active biasing circuit |
| 2, 3, 6, 8, 9, 10, 13, 14 | GND | RF and DC ground. |
| 4 | VCC1 | Bias voltage for current mirror in combination with Vref to set the bias point. |
| 5 | RFin | RF input pin. The DC is internally blocked at this pin. |
| 7 | NC | No internal connection. Can be left open or grounded for mounting integrity. |
| 11 | VCC2 | Supply to all stages. |
| 12 | RFout | RF output pin. The DC is internally blocked at this pin. |
| Backside Paddle | RF/DC GND | RF/DC ground. See PCB Mounting Pattern for suggested footprint. |

Evaluation Board PCB Information

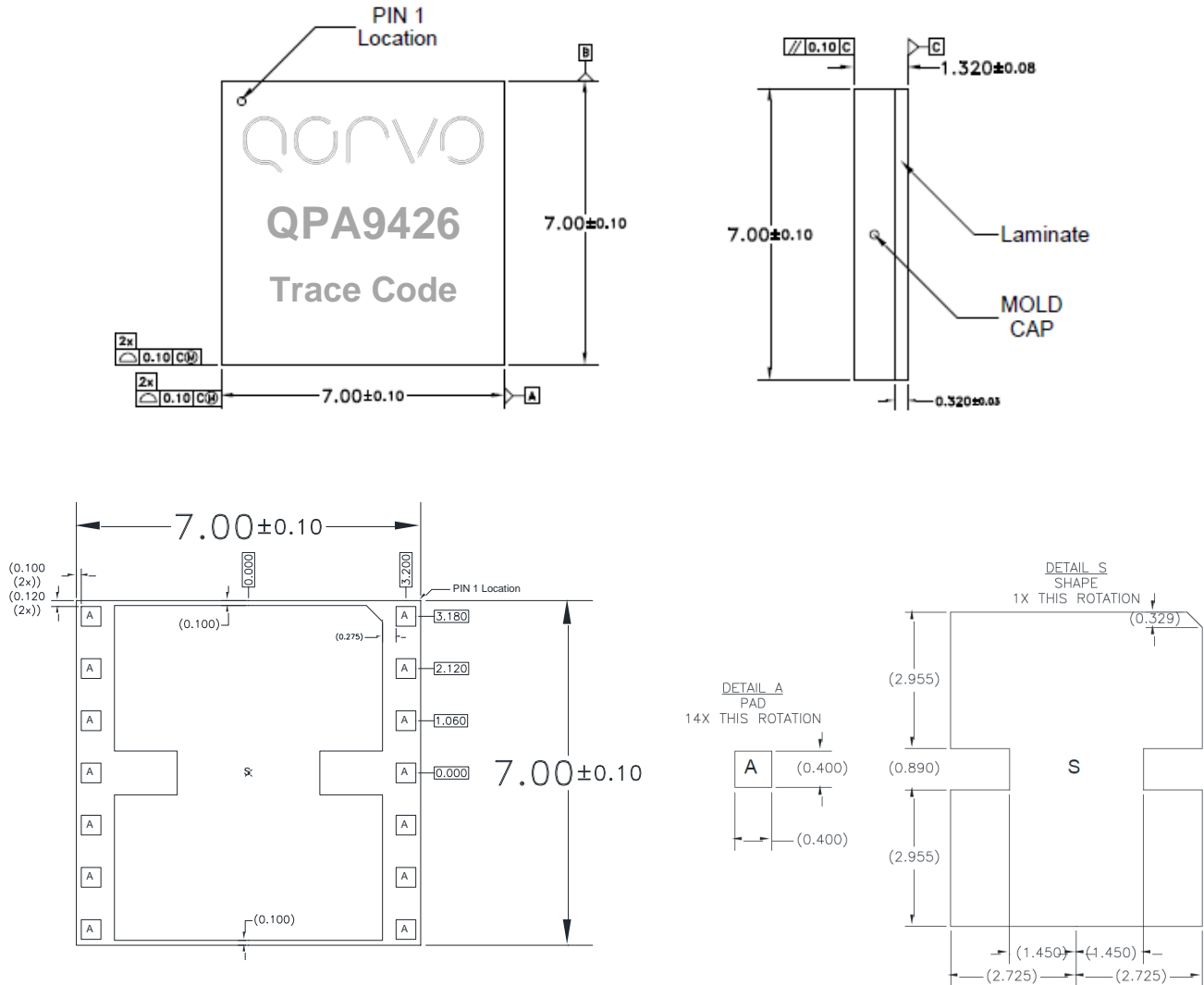
Qorvo PCB 1126637 Material and Stack-up



50 ohm line dimensions: width = .028"
 spacing = .028".



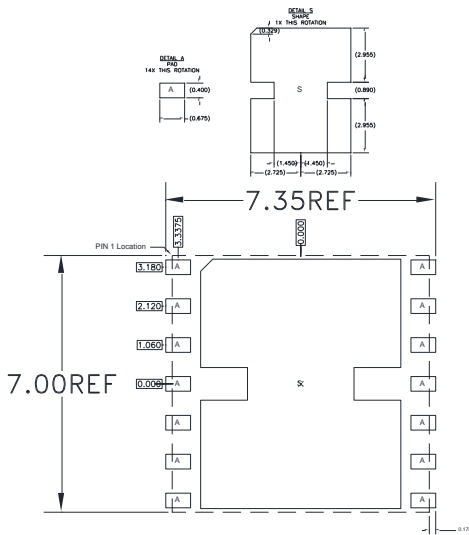
Package Marking and Dimensions



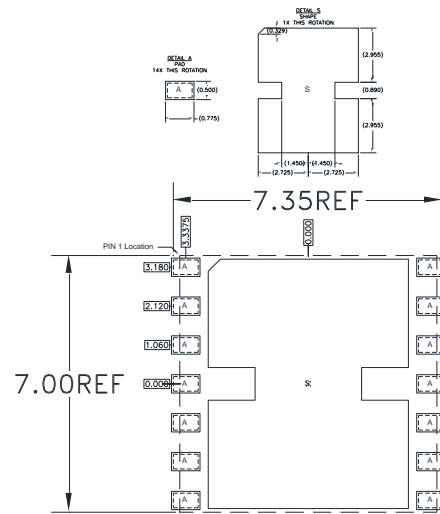
Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.

PCB Mounting Pattern



**RECOMMENDED
 LAND PATTERN**



**RECOMMENDED
 LAND PATTERN MASK**

Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|----------|--------------------------|
| ESD – Human Body Model (HBM) | Class 2 | ESDA / JEDEC JS-001-2012 |
| ESD – Charged Device Model (CDM) | Class C3 | JEDEC JESD22-C101F |
| MSL – Moisture Sensitivity Level | Level 3 | IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes.

Solder profiles available upon request.

Contact plating: Electrolytic plated Au over Ni

RoHS Compliance

This part is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU. This product also has the following attributes:

- Product uses RoHS Exemption 7c-I to meet RoHS Compliance requirements.
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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Web: www.qorvo.com

Email: customer.support@qorvo.com

For technical questions and application information: **Email: sicapplications.engineering@qorvo.com**

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